

1-2-02

PATENT

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Attorney Docket No. MICRON.076DV1

Date: December 27, 2001

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COMMISSIONER FOR PATENTS

WASHINGTON, D.C. 20231

ATTENTION: BOX PATENT APPLICATION

Sir:

Transmitted herewith for filing is the patent application of

Inventors: Li

For:

LOW DIELECTRIC CONSTANT MATERIAL FOR INTEGRATED CIRCUIT FABRICATION

Enclosed are:

- (X) 10 sheets of drawing.
- (X) This application is a divisional of prior application 09/146,397, September 3, 1998.
- (X) A copy of Declaration from prior application is enclosed.
- (X) Incorporation by Reference. The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.
- (X) Initial signed declaration by inventor(s).
- (X) Return prepaid postcard.

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$740	\$740
Total Claims	10 - 20 =	0 ×	\$18	\$0
Independent Claims	2 - 3 =	0 ×	\$84	\$0
If application contains any multiple dependent claims(s), then add			\$280	\$0
TOTAL FILING FEE		\$740		

31025 U.S. PTO
12/27/01

31000 U.S. PTO
10/033656
12/27/01

4003656-12/27/01

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- Cheryl Lynn Althoff

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BOX PATENT APPLICATION
Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Attorney Docket No. : MICRON.076DV1
Applicant(s) : Li
For : LOW DIELECTRIC CONSTANT MATERIAL
FOR INTEGRATED CIRCUIT
FABRICATION
Attorney : Adeel S. Akhtar
"Express Mail"
Mailing Label No. : EL 544396734 US
Date of Deposit : December 27, 2001

I hereby certify that the accompanying

Transmittal letter; specification in 18 pages; 10 sheets of drawings; **SIGNED**
Declaration by Inventor in 1 pages; Check for Filing Fee; Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.


Jonathan Pan

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